

ABSTRACT

Provided are an apparatus for and a method of removing foreign materials from a substrate which reliably remove the foreign materials, eliminate a chance of redeposition of the foreign materials, and are applicable even to large-size substrates. The apparatus for removing foreign materials includes electrostatic chucks (2, 3) forming a substrate chucking surface (4) to which the substrate (1) is attracted; a resin sheet supplying means (9) for supplying a resin sheet (5) to the substrate chucking surface (4); resin sheet collecting means (13) for collecting the supplied resin sheet (5); and a substrate transfer means for transferring the substrate (1). The substrate (1) supplied to the electrostatic chucks (2, 3) by the substrate transfer means is attracted to the substrate chucking surface (4) through the resin sheet (5), and a foreign material (22) deposited on a side of the substrate chucking surface (4) of the substrate (1) is transferred onto the resin sheet (5) and removed.